Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	540	thin adj film near1 inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 11:34
S2	301	resist adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 13:09
S3	142	photoresist adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/09 12:43
S4	410	S2 S3	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 13:09
S5	13	S1 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/09 12:43
S6	1036	(resist near1 frame) (photoresist near1 frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/16 14:53
S7	325	S6 with (plating plat$4 electroplat$4 electroplating)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 13:10
S8	4	S7 same repeat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 13:10
S9	189	S6 with second	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 13:46
S10	187	S9 not S8	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 14:48
S11	1175	prevent$4 near1 intermix$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 14:48

S12	0	S10 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/14 14:48
S13	2	("2000132812").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/15 11:47
S14	2	("6666981").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/15 11:52
S15	2	("6641984").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/15 11:52
S16	2	("6785953").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/15 11:55
S17	2	("20030219980").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/09/15 12:57
S18	308	intermix$4 with photoresist$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:18
S19	38	S18 same (plat$4 electroplat$)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:18
S20	375	bilayer$4 with photoresist$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:18
S21	26	S20 same (plat$4 electroplat$)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:19
S22	26	S21 not S19	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:28
S23	5750104	(conductive conducting conductor metal metallization metallic (plating near1 base) electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:30

S24	419043	S23 with cover$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:33
S25	13348	S24 with frame	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 13:34
S26	134	S25 with (photoresist resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:03
S27	1255	(plating near1 frame) (electroplat$4 near1 frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/16 14:54
S28	0	S27 with intermix$4	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:03
S29	3	S27 with bilayer	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:04
S30	1	S27 with dual	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:05
S31	929	S23 and S27	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:06
S32	645	S31 and (magnetic inductor coil micro)	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:06
S33	725	S31 and @ad<"20020719"	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:07
S34	485	S32 and S33	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/15 14:30
S35	18	S32 and S33	JPO	OR	ON	2005/09/15 14:30
S36	517025	"216"/$.ccls. "29"/$.ccls. "438"/$.ccls.."205"/$.ccls. "430"/$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/09/16 14:53

S37	1036	(resist near1 frame) (photoresist near1 frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:54
S38	1255	(plating near1 frame) (electroplat$4 near1 frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:54
S39	2092	S37 S38	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:54
S40	414	S36 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:54
S41	164	(resist near1 frame).clm. (photoresist near1 frame) .clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:54
S42	81	(plating near1 frame).clm. (electroplat$4 near1 frame).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:55
S43	232	S41 S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:55
S44	73	S43 and S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 14:55